

JAN 13 2007

Appl. No. 10/840,095  
Amdt. dated 01/13/2007  
Response to Office Action of 10/17/2006

Attorney Docket No.: N1085-00288  
[TSMC2004-0032]

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: **Chao-Lung Chen**

Examiner: **Thanh T. Nguyen**

Serial No.: **10/840,095**

Group Art Unit: **2813**

Filed: **05/06/2004**

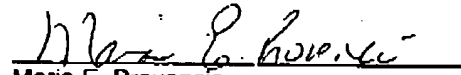
Confirmation No.: **7304**

**For: COPPER PLATING OF SEMICONDUCTOR DEVICES USING SINGLE  
INTERMEDIATE LOW POWER IMMERSION STEP (As Amended)**

**CERTIFICATE OF MAILING/FACSIMILE TRANSMISSION PURSUANT TO 37 C.F.R. §1.8**

I hereby certify that this correspondence (and anything referred to as being transmitted herewith) is being facsimile transmitted to the United States Patent and Trademark Office (Fax No. 571-273-8300) on the date shown below.

Date: January 13, 2007

  
Maria E. Provencio

Examiner Thanh T. Nguyen  
Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO OFFICE ACTION DATED OCTOBER 17, 2006  
EXPEDITED PROCEDURE – 37 CFR § 1.116**

Commissioner:

Responsive to the final Office Action dated October 17, 2006, please re-examine and reconsider the above-identified application according to the amendments and remarks provided.

**Amendments to the Specification** are shown on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.